2SC1684, 2SC1685

Silicon NPN Epitaxial Planar Type

For general amplification

Features

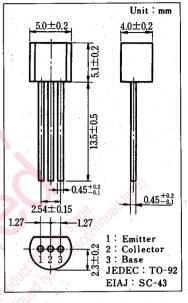
•High DC current gain h_{FE}

•Low collector-emitter saturation voltage $V_{CE(sat)}$

■ Absolute Maximum Ratings (Ta=25°C)

Item		Symbol	Value	Unit	
Collector-Base	2SC1684	V	30	V	
Voltage	2SC1685	V _{CBO}	60		
Collector-Emitter Voltage	2SC1684	V	25	V	
	2SC1685	V _{ceo}	50		
Emitter-Base Voltage		Vebo	7	V	
Peak Collector Voltage		I _{CP}	200	mA	
Collector Current		Ic	100	mA	
Collector Power Dissipation		Pc	400	mW	
Junction Temperature		T _i	150	C	
Storage Temperature		T _{stg}	-55 - +150	C	





■ Electrical Characteristics (Ta=25°C)

Item		Symbol Condition		min.	typ.	max.	Unit
Collector Cutoff Current		I _{CBO}	$V_{cB} = 10 V, I_{E} = 0$			1	μA
		I _{CEO}	$V_{cE} = 10 V, I_B = 0$			100	μA
Collector-Base	illector-Base 2SC1684		30			v	
Voltage	2SC1685	V _{сво}	$I_{c} = 10 \ \mu A, \ I_{E} = 0$	60			
Collector-Emitter Voltage	2SC1684	- V _{CEO}	$I_c = 2 \text{ mA}, I_B = 0$	25			v
	2SC1685			50			
Emitter-Base Voltage		V _{EBO}	$I_{\rm E} = 10 \mu {\rm A}, \ I_{\rm C} = 0$	7			V
DC Current Gain		h _{FE1} *	$V_{ce} = 10 V, I_c = 2 mA$	160		460	
		h _{FE2}	$V_{ce} = 2 V, I_c = 100 mA$	90			
Collector-Emitter Satu	ration Voltage	V _{CE(sat)}	$I_c = 100 \text{ mA}, I_B = 10 \text{ mA}$		0.3	0.5	V .,
Transition Frequency		f _T	$V_{CB}=10V, I_{E}=-2mA, f=200MHz$		150		MHz
Noise Voltage		NV	$V_{cE} = 10 \text{ V}, I_c = 1 \text{ mA}, G_v = 80 \text{ dB}$ $R_g = 100 \text{ k}\Omega, \text{ Function} = \text{FLAT}$		300		mV
Collector Output Capacitance		Соь	$V_{cB} = 10 V$, $I_E = 0$, $f = 1 MHz$		3.5		pF

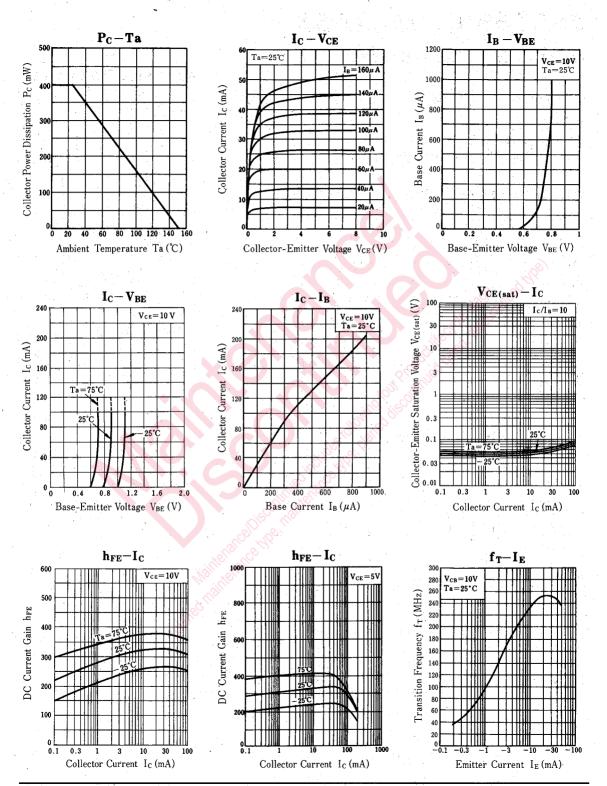
* h_{FE1} Ranking

Rank	Q	R	S
h _{FE1}	160~260	200~340	290~460

Panasonic

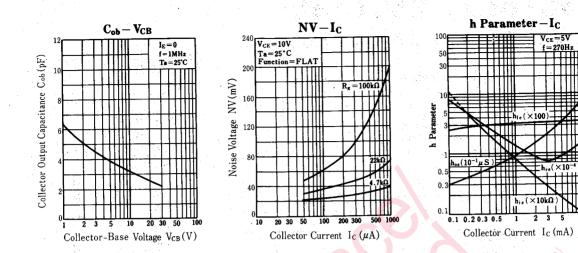
Transistors

2SC1684, 2SC1685



Transistors

2SC1684, 2SC1685



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